



GCCAF-01 Aluminum-base copper-clad laminate

Test base: GCCAF-01 the high heat dissipation Aluminum-base copper-clad laminate

Thickness of copper: 35um

Thickness of dielectric: 70um

Thickness of aluminum-base: 1.5mm

Test result:

Item	Test item		Technology request	Unit	Test result
1	Peel Strength	A	≥ 1.8	N/mm	2.0
		After Thermal stress (260°C)	≥ 1.8	N/mm	1.8
2	Blister test After Thermal stress (260°C, 2min)		No delamination	/	Pass
3	Thermal resistance		≤ 2.0	°C/W	1.0
4	Thermal-Conductive Factor		/	W/mk	1.0
5	Flammability(A)		V-O	/	V-O
6	Surface Resistivity	A	$\geq 1 \times 10^5$	MΩ	5×10^7
		Constant humidity treatment (90%,35°C, 96h)	$\geq 1 \times 10^5$	MΩ	2×10^6
7	Volume Resistivity	A	$\geq 1 \times 10^6$	MΩ m	4×10^8
		Constant humidity treatment (90%,35°C, 96h)	$\geq 1 \times 10^6$	MΩ m	5×10^7
8	Dielectric Breakdown (DC)		≥ 28.5	Kv/mm	31
9	Dielectric constant (1MHz) (40°C, 93%, 96h)		≤ 4.4	/	4.2
10	Dielectric dissipation factor (1MHz) (40°C, 93%, 96h)		≤ 0.03	/	0.02